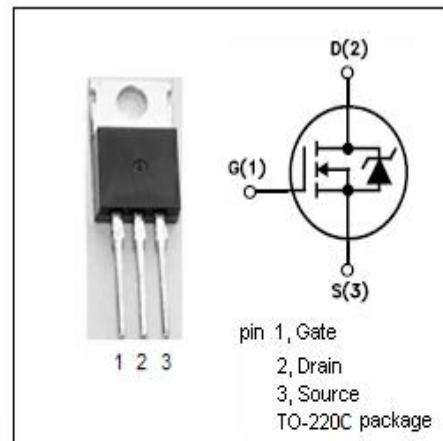


isc N-Channel MOSFET Transistor

FDP2532
• FEATURES

- With TO-220 packaging
- High speed switching
- Low gate input resistance
- Standard level gate drive
- Easy to use
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation


• APPLICATIONS

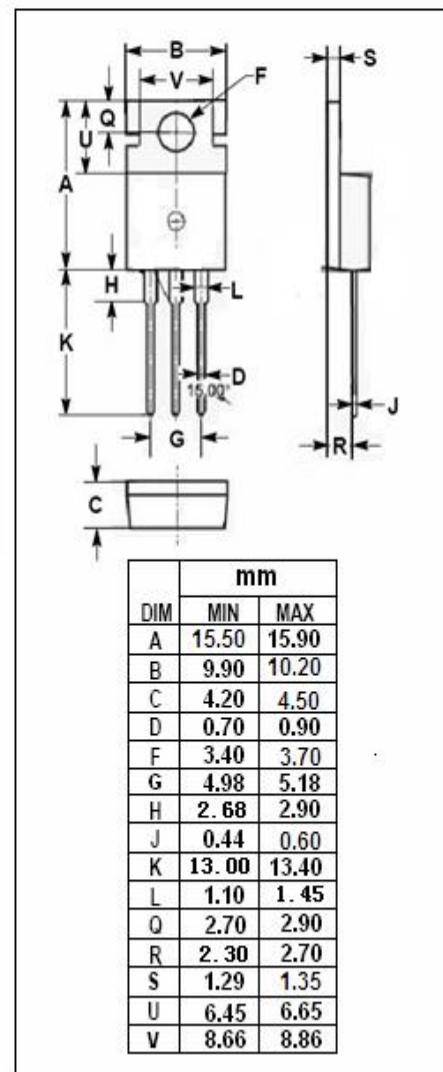
- Power supply
- Switching applications

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	150	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous;@ $T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	79 56	A
I_{DM}	Drain Current-Single Pulsed	300	A
P_D	Total Dissipation	310	W
T_j	Operating Junction Temperature	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~175	$^\circ\text{C}$

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	0.48	$^\circ\text{C}/\text{W}$
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	62	$^\circ\text{C}/\text{W}$



isc N-Channel MOSFET Transistor**FDP2532****ELECTRICAL CHARACTERISTICS** $T_c=25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}; I_{\text{D}}= 0.25\text{mA}$	150			V
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}; I_{\text{D}}=0.25\text{mA}$	2.0		4.0	V
$R_{\text{DS}(\text{on})}$	Drain-Source On-Resistance	$V_{\text{GS}}= 10\text{V}; I_{\text{D}}=33\text{A}$		14	16	$\text{m}\Omega$
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}; V_{\text{DS}}= 0\text{V}$			± 0.1	μA
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}= 120\text{V}; V_{\text{GS}}= 0\text{V}; T_j=25^\circ\text{C}$ $V_{\text{DS}}= 120\text{V}; V_{\text{GS}}= 0\text{V}; T_j=150^\circ\text{C}$			1 250	μA
V_{SDF}	Diode forward voltage	$I_{\text{SD}}=1\text{A}, V_{\text{GS}} = 0 \text{ V}$			1.0	V